To the Director of the U.S. Patent and Trademark Office: Pies	ttached documents or the new address(es) below
1. Name of conveying party(ies)/Execution Date(s):	2. Name and address of receiving party(ies)
	Name: Sony Computer Entertainment America Inc.
Andrew Graham Styles	Internal Address:
Execution Date(s) August 1, 2005  Additional name(s) of conveying party(ies) attached? Yes V  3. Nature of conveyance:	Street Address: 919 E. Hillsdale Boulevard, 2nd Floo
Assignment Merger	City: Foster City
Security Agreement Change of Name	State: California
Government Interest Assignment Executive Order 9424, Confirmatory License	Country: <u>U.S.</u> Zip: <u>94404-2175</u>
Other	Additional name(s) & address(es) attached? Yes
A. Patent Application No.(s)	
Additional numbers a  5. Name and address to whom correspondence	6. Total number of applications and patents
Additional numbers a  5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Additional numbers a  5. Name and address to whom correspondence	6. Total number of applications and patents
Additional numbers a  5. Name and address to whom correspondence concerning document should be mailed: Name: Fitch, Even, Tabin & Flannery	6. Total number of applications and patents involved:  7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00  Authorized to be charged by credit card  Authorized to be charged to deposit account  Enclosed
Additional numbers a  5. Name and address to whom correspondence concerning document should be mailed:  Name: Fitch, Even, Tabin & Flannery  Internal Address:  Street Address: 120 South La Salle Street, Suite 1600	6. Total number of applications and patents involved:  7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00  Authorized to be charged by credit card  Authorized to be charged to deposit account  Enclosed
Additional numbers a  5. Name and address to whom correspondence concerning document should be mailed: Name: Fitch, Even, Tabin & Flannery Internal Address:	6. Total number of applications and patents involved:  7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00  Authorized to be charged by credit card  Authorized to be charged to deposit account  Enclosed  None required (government interest not affecting
Additional numbers a  5. Name and address to whom correspondence concerning document should be mailed:  Name: Fitch, Even, Tabin & Flannery  Internal Address:  Street Address: 120 South La Salle Street, Suite 1600  City: Chicago	6. Total number of applications and patents involved:  7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00  Authorized to be charged by credit card  Authorized to be charged to deposit account  Enclosed  None required (government interest not affecting)  8. Payment Information  a. Credit Card Last 4 Numbers  Expiration Date
Additional numbers a  5. Name and address to whom correspondence concerning document should be mailed:  Name: Fitch, Even, Tabin & Flannery  Internal Address:  Street Address: 120 South La Salle Street, Suite 1600  City: Chicago  State: Illinois Zip: 60603-3406	6. Total number of applications and patents involved:  7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00  Authorized to be charged by credit card  Authorized to be charged to deposit account  Enclosed  None required (government interest not affecting)  8. Payment Information  a. Credit Card Last 4 Numbers  Expiration Date  b. Deposit Account Number 06-1135
Additional numbers a  5. Name and address to whom correspondence concerning document should be mailed:  Name: Fitch, Even, Tabin & Flannery  Internal Address:  Street Address: 120 South La Salle Street, Suite 1600  City: Chicago  State: Illinois Zip: 60603-3406  Phone Number: 858-552-1311	6. Total number of applications and patents involved:  7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00  Authorized to be charged by credit card  Authorized to be charged to deposit account  Enclosed  None required (government interest not affecting)  8. Payment Information  a. Credit Card Last 4 Numbers  Expiration Date
Additional numbers a  5. Name and address to whom correspondence concerning document should be mailed:  Name: Fitch, Even, Tabin & Flannery  Internal Address:  Street Address: 120 South La Salle Street, Suite 1600  City: Chicago  State: Illinois Zip: 60603-3406  Phone Number: 858-552-0095	6. Total number of applications and patents involved:  7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00  Authorized to be charged by credit card  Authorized to be charged to deposit account  Enclosed  None required (government interest not affecting)  8. Payment Information  a. Credit Card Last 4 Numbers  Expiration Date  b. Deposit Account Number 06-1135

PATENT REEL: 016865 FRAME: 0511

## Docket No. \_81891 [SCEA04015US00]

## ASSIGNMENT

WHEREAS, I, as a below named inventor, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in CONSTRAINT SCHEMES FOR COMPUTER SIMULATION OF CLOTH AND OTHER MATERIALS for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Computer Entertainment America Inc., a Delaware corporation with offices at 919 E. Hillsdale Boulevard, 2<sup>ND</sup> Floor, Foster City, California 94404-2175 (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEB will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto:

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

date, serial number and filing date of this application in the spaces that follow: Serial Number:  This assignment is being executed on the date indicated below.	
[Name of first or sole inventor]	[Execution date of U.S. Patent Application]
San Diego, California	
[Residence]	
<b>4</b> 0.	8-1-2008
[Signature of first or sole inventor]	[Date of this Assignment]

PATENT REEL: 016865 FRAME: 0512